

ABSTRACT

APPARATUS AND METHOD FOR SEMICONDUCTOR CHIP DETACHMENT

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10 An apparatus and method is provided for detaching a semiconductor chip from an adhesive tape on which it is mounted. The apparatus comprises a platform adapted to contact the adhesive tape at a position of the chip and a retaining force generator coupled to the platform for drawing the adhesive tape in a direction away from the chip. An elevation device is projectable from the platform that is movable both laterally across a surface of the platform and vertically with respect to the platform for elevating the chip. By moving the elevation device across a width of the chip while lifting the chip, controlled
15 lifting of the chip and propagation of delamination between the chip and the adhesive tape may be achieved.

(Figure 1)